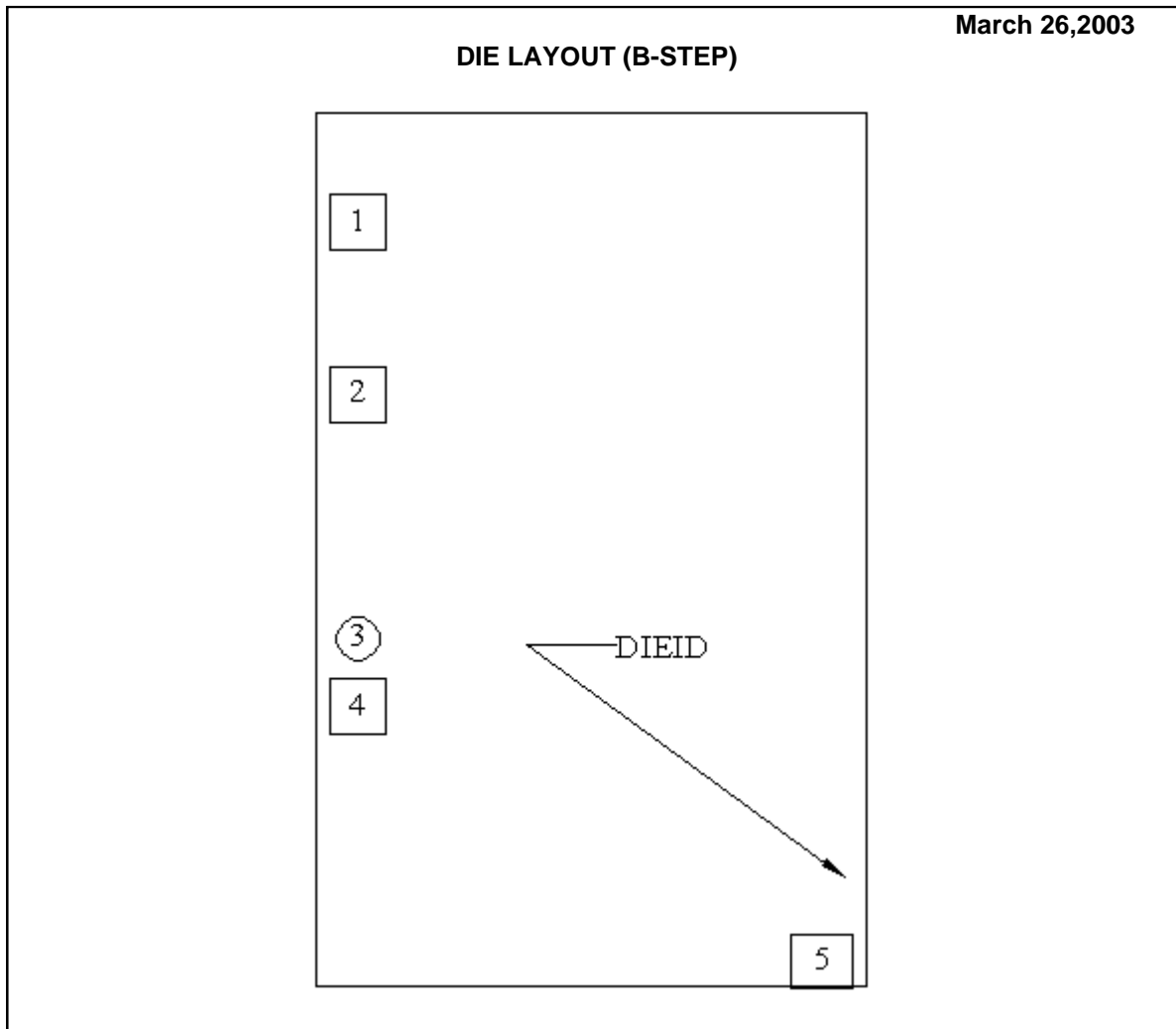


LM337L MDC MWC
3-TERMINAL ADJUSTABLE REGULATOR



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	80B	Bond Pad Opening Size (min)	117 μ m x 117 μ m
Die Step	B	Bond Pad Metalization	0.5% COPPER_BAL. ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1168 μ m x 1854 μ m 46.0mils x 73.0mils	Back Side Connection	VIN
Thickness	406 μ m Nominal		
Min Pitch	144 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	XY COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
ADJ	1	-495	693	117	x	117
V _{OUT}	2	-495	328	117	x	117
NC	3	-495	-191	91	x	91
V _{IN}	4	-495	-335	117	x	117
V _{OUT}	5	489	-876	130	x	117

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